

200V N-Channel Enhancement Mode MOSFET

General Features

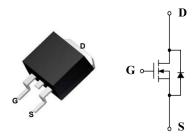
- > Reliable and Rugged
- ► Lead Free and Green Devices Available
- ➤ RoHS Compliant
- > Halogen-free available
- ➤ Moisture Sensitivity Level MSL1

Applications

- > Synchronous Rectification
- > Power Management in Inverter Systems
- ➤ DC/DC Converter

BV _{DSX}	R _{DS(ON)} (Max.)	I_D		
200V	11m Ω	102A		

TO-263-2



Ordering Information

Part Number	Package	Marking	Remark	
FTB200N11	TO-263-2	200N11	Halogen Free	

Absolute Maximum Ratings

TA =25°C unless otherwise specified

Symbol	Parameter	FTB200N11	Unit	
V_{DSS}	Drain-to-Source Voltage	200	V	
V_{GSS}	Gate-to-Source Voltage	±20	V	
I_S	Diode Continuous Forward Current	T _C =25 ℃	51	
I_D	Continuous Drain Current	T _C =25 ℃	102	A
$I_{DM}^{[1]}$	Pulsed Drain Current	T _C =25 °C	306	
T_{J}	Maximum Junction Temperature		150	%
T_{STG}	Storage Temperature Range	-55 to 150	\mathbb{C}	



Electrical Characteristics

Static Characteristics

TA =25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	
BV _{DSX}	Drain-to-Source Breakdown Voltage	200	-	-	V	V _{GS} =0V, I _{DS} =250 μA	
T	Zone Cata Walters Dunin Comment	-	-	1	μА	V _{DS} =160V,	
I_{DSS}	Zero Gate Voltage Drain Current	-	-	30		$V_{GS}=0V$ $T_{J}=85^{\circ}C$	
V _{GS(th)}	Gate Threshold Voltage	2	3	4	V	$V_{DS}=V_{GS},~I_{DS}=250~\mu A$	
I_{GSS}	Gate Leakage Current	-	-	±100	nA	$V_{GS}=\pm20V, V_{DS}=0V$	
R _{DS(ON)} [2]	Drain-to-Source On-state Resistance	-	10	11	mΩ	V _{GS} =10V, I _{DS} =50A	

Diode Characteristics

TA =25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
$V_{SD}^{[2]}$	Diode Forward Voltage	-	0.8	-	V	I_{SD} =25A, V_{GS} =0V

Dynamic Characteristics [3]

TA =25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
R_{G}	Gate Resistance	-	2	-	Ω	$V_{GS}=0V, V_{DS}=0V, F=1MHz$
Ciss	Input Capacitance	-	6826	-	pF	V _{GS} =0V, V _{DS} =100V, F=1.0MHz
Coss	Output Capacitance	-	356	-		
C _{rss}	Reverse Transfer Capacitance	-	46	-		

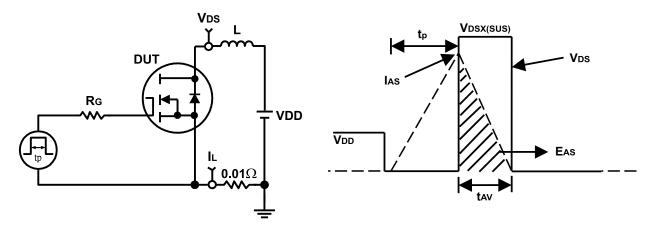
Note [1]: Pulse width is limited by maximum junction temperature.

Note [2]: Pulse test; pulse width \(\le 300\text{us, duty cycle} \(\le 2\)%.

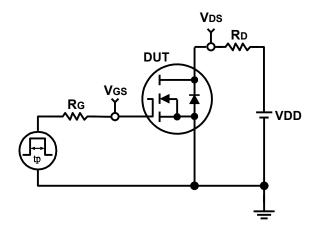
Note [3]: Guaranteed by design, not subject to production testing.

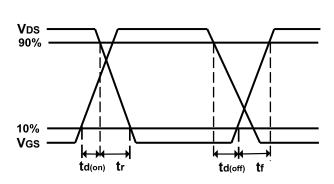


Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms

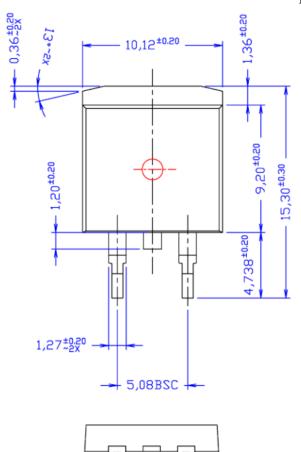


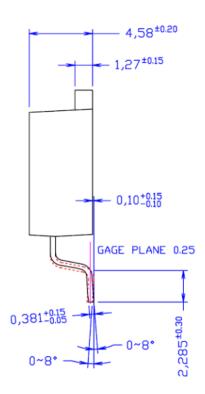




Package Dimensions

TO-263-2







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